



Material Content Data Sheet



Sales Product Name		BG 3130 H6327		Issued		20. July 2018		
MA#		MA001314872						
Package		PG-SOT363-6-4		Weight*		6.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.08		816	
	non noble metal	tin	7440-31-5	0.001	0.02		210	
	inorganic material	silicon	7440-21-3	0.042	0.68	0.78	6759	7785
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1374	
	non noble metal	copper	7440-50-8	2.860	45.61	45.81	456127	458051
wire	non noble metal	copper	7440-50-8	0.014	0.22	0.22	2215	2215
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4884	
	plastics	epoxy resin	-	0.658	10.50		105005	
	inorganic material	silicondioxide	60676-86-0	2.373	37.85	48.84	378506	488395
leadfinish	non noble metal	tin	7440-31-5	0.213	3.40	3.40	34008	34008
plating	noble metal	silver	7440-22-4	0.060	0.95	0.95	9546	9546
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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